



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q67726

Mitsuo OSADA, et al.

Appln. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: LAVILLA, MICHAEL E

Filed: December 13, 2001

For: MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC PACKAGE USING THE SAME

**AMENDMENT UNDER 37 C.F.R. § 1.111**

**MAIL STOP NON-FEE AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated June 4, 2003, please amend the above-identified application as follows on the accompanying pages.